



Material Content Data Sheet



Sales Product Name				IPC100N04S5L-1R5		Issued		24. January 2018	
MA#				MA001357936					
Package				PG-TDSON-8-34		Weight*		112.66 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.077	0.96	0.96	9556	9556	
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		142		
	non noble metal	iron	7439-89-6	0.053	0.05		472		
	non noble metal	copper	7440-50-8	53.151	47.16	47.22	471780	472394	
	noble metal	gold	7440-57-5	0.044	0.04	0.04	389	389	
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	389	389	
encapsulation	organic material	carbon black	1333-86-4	0.075	0.07		667		
	plastics	epoxy resin	-	5.936	5.27		52693		
	inorganic material	silicondioxide	60676-86-0	31.561	28.01	33.35	280139	333499	
leadfinish	non noble metal	tin	7440-31-5	1.574	1.40	1.40	13969	13969	
plating	noble metal	silver	7440-22-4	0.209	0.19	0.19	1857	1857	
solder	non noble metal	tin	7440-31-5	0.030	0.03		262		
	noble metal	silver	7440-22-4	0.037	0.03		328		
	non noble metal	lead	7439-92-1	1.410	1.25	1.31	12515	13105	
CLIP plating	noble metal	silver	7440-22-4	0.639	0.57	0.57	5672	5672	
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.005	0.00		45		
	non noble metal	iron	7439-89-6	0.017	0.02		150		
	non noble metal	copper	7440-50-8	16.828	14.94	14.96	149364	149559	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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